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Details	
Product Status	Active
Core Processor	HC11
Core Size	8-Bit
Speed	3MHz
Connectivity	SCI, SPI
Peripherals	POR, WDT
Number of I/O	30
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	4.75V ~ 5.25V
Data Converters	A/D 8x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.21x24.21)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mchc11f1vfne3

Table 2-1 Port Signal Functions

Port/Bit	Single-Chip and Bootstrap Mode	Expanded and Special Test Mode
PA0	PA0/IC3	
PA1	PA1/IC2	
PA2	PA2/IC1	
PA3	PA3/OC5/IC4/OC1	
PA4	PA4/OC4/OC1	
PA5	PA5/OC3/OC1	
PA6	PA6/OC2/OC1	
PA7	PA7/PAI/OC1	
PB[7:0]	PB[7:0]	ADDR[15:8]
PC[7:0]	PC[7:0]	DATA[7:0]
PD0	PD0/RxD	
PD1	PD1/TxD	
PD2	PD2/MISO	
PD3	PD3/MOSI	
PD4	PD4/SCK	
PD5	PD5/$\overline{SS}$	
PE[7:0]	PE[7:0]/AN[7:0]	
PF[7:0]	PF[7:0]	ADDR[7:0]
PG0	PG0	
PG1	PG1	
PG2	PG2	
PG3	PG3	
PG4	PG4	PG4/CSIO2
PG5	PG5	PG5/CSIO1
PG6	PG6	PG6/CSGEN
PG7	PG7	PG7/$\overline{CSPROG}$

2.11.1 Port A

Port A is an 8-bit general-purpose I/O port with a data register (PORTA) and a data direction register (DDRA). Port A pins share functions with the 16-bit timer system. PORTA can be read at any time. Inputs return the pin level; outputs return the pin driver input level. If written, PORTA stores the data in internal latches. It drives the pins only if they are configured as outputs. Writes to PORTA do not change the pin state when the pins are configured for timer output compares.

Out of reset, port A pins [7:0] are general-purpose high-impedance inputs. When the timer functions associated with these pins are disabled, the bits in DDRA govern the I/O state of the associated pin. For further information, refer to **SECTION 6 PARALLEL INPUT/OUTPUT**.

NOTE

When using the information about port functions, do not confuse pin function with the electrical state of the pin at reset. All general-purpose I/O pins configured as inputs at reset are in a high-impedance state. Port data registers reflect the logic state of the port at reset. The pin function is mode dependent.

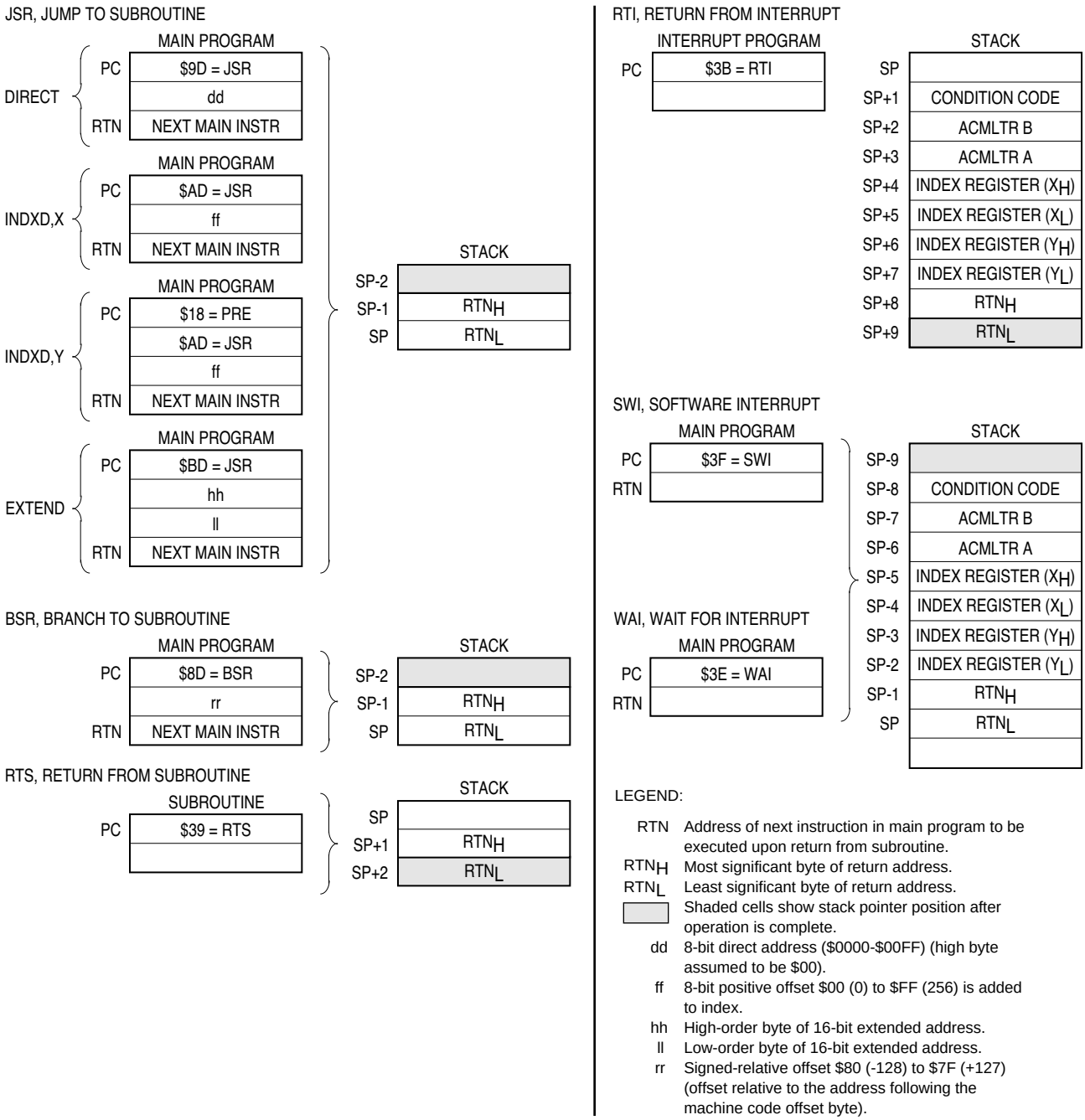

Figure 3-2 Stacking Operations

When a subroutine is called by a jump to subroutine (JSR) or branch to subroutine (BSR) instruction, the address of the instruction after the JSR or BSR is automatically pushed onto the stack, least significant byte first. When the subroutine is finished, a return from subroutine (RTS) instruction is executed. The RTS pulls the previously stacked return address from the stack, and loads it into the program counter. Execution then continues at this recovered return address.

3.1.6.3 Zero (Z)

The Z bit is set if the result of an arithmetic, logic, or data manipulation operation is zero. Otherwise, the Z bit is cleared. Compare instructions do an internal implied subtraction and the condition codes, including Z, reflect the results of that subtraction. A few operations (INX, DEX, INY, and DEY) affect the Z bit and no other condition flags. For these operations, only = and - conditions can be determined.

3.1.6.4 Negative (N)

The N bit is set if the result of an arithmetic, logic, or data manipulation operation is negative (MSB = 1). Otherwise, the N bit is cleared. A result is said to be negative if its most significant bit (MSB) is a one. A quick way to test whether the contents of a memory location has the MSB set is to load it into an accumulator and then check the status of the N bit.

3.1.6.5 Interrupt Mask (I)

The interrupt request (IRQ) mask (I bit) is a global mask that disables all maskable interrupt sources. While the I bit is set, interrupts can become pending, but the operation of the CPU continues uninterrupted until the I bit is cleared. After any reset, the I bit is set by default and can only be cleared by a software instruction. When an interrupt is recognized, the I bit is set after the registers are stacked, but before the interrupt vector is fetched. After the interrupt has been serviced, a return from interrupt instruction is normally executed, restoring the registers to the values that were present before the interrupt occurred. Normally, the I bit is zero after a return from interrupt is executed. Although the I bit can be cleared within an interrupt service routine, “nesting” interrupts in this way should only be done when there is a clear understanding of latency and of the arbitration mechanism. Refer to **SECTION 5 RESETS AND INTERRUPTS**.

3.1.6.6 Half Carry (H)

The H bit is set when a carry occurs between bits 3 and 4 of the arithmetic logic unit during an ADD, ABA, or ADC instruction. Otherwise, the H bit is cleared. Half carry is used during BCD operations.

3.1.6.7 X Interrupt Mask (X)

The $\overline{\text{XIRQ}}$ mask (X) bit disables interrupts from the $\overline{\text{XIRQ}}$ pin. After any reset, X is set by default and must be cleared by a software instruction. When an $\overline{\text{XIRQ}}$ interrupt is recognized, the X and I bits are set after the registers are stacked, but before the interrupt vector is fetched. After the interrupt has been serviced, an RTI instruction is normally executed, causing the registers to be restored to the values that were present before the interrupt occurred. The X interrupt mask bit is set only by hardware ($\overline{\text{RESET}}$ or $\overline{\text{XIRQ}}$ acknowledge). X is cleared only by program instruction (TAP, where the associated bit of A is zero; or RTI, where bit 6 of the value loaded into the CCR from the stack has been cleared). There is no hardware action for clearing X.

Table 3-2 Instruction Set (Sheet 2 of 6)

Mnemonic	Operation	Description	Addressing Mode	Instruction			Condition Codes							
				Opcode	Operand	Cycles	S	X	H	I	N	Z	V	C
BGT (rel)	Branch if > Zero	? Z + (N ⊕ V) = 0	REL	2E	rr	3	—	—	—	—	—	—	—	—
BHI (rel)	Branch if Higher	? C + Z = 0	REL	22	rr	3	—	—	—	—	—	—	—	—
BHS (rel)	Branch if Higher or Same	? C = 0	REL	24	rr	3	—	—	—	—	—	—	—	—
BITA (opr)	Bit(s) Test A with Memory	A • M	A IMM A DIR A EXT A IND,X A IND,Y	85 95 B5 A5 18 A5	ii dd hh ll ff ff	2 3 4 4 5	—	—	—	—	Δ	Δ	0	—
BITB (opr)	Bit(s) Test B with Memory	B • M	B IMM B DIR B EXT B IND,X B IND,Y	C5 D5 F5 E5 18 E5	ii dd hh ll ff ff	2 3 4 4 5	—	—	—	—	Δ	Δ	0	—
BLE (rel)	Branch if Δ Zero	? Z + (N ⊕ V) = 1	REL	2F	rr	3	—	—	—	—	—	—	—	—
BLO (rel)	Branch if Lower	? C = 1	REL	25	rr	3	—	—	—	—	—	—	—	—
BLS (rel)	Branch if Lower or Same	? C + Z = 1	REL	23	rr	3	—	—	—	—	—	—	—	—
BLT (rel)	Branch if < Zero	? N ⊕ V = 1	REL	2D	rr	3	—	—	—	—	—	—	—	—
BMI (rel)	Branch if Minus	? N = 1	REL	2B	rr	3	—	—	—	—	—	—	—	—
BNE (rel)	Branch if not = Zero	? Z = 0	REL	26	rr	3	—	—	—	—	—	—	—	—
BPL (rel)	Branch if Plus	? N = 0	REL	2A	rr	3	—	—	—	—	—	—	—	—
BRA (rel)	Branch Always	? 1 = 1	REL	20	rr	3	—	—	—	—	—	—	—	—
BRCLR(opr) (msk) (rel)	Branch if Bit(s) Clear	? M • mm = 0	DIR IND,X IND,Y	13 1F 18 1F	dd mm rr ff mm rr ff mm rr	6 7 8	—	—	—	—	—	—	—	—
BRN (rel)	Branch Never	? 1 = 0	REL	21	rr	3	—	—	—	—	—	—	—	—
BRSET(opr) (msk) (rel)	Branch if Bit(s) Set	? (M) • mm = 0	DIR IND,X IND,Y	12 1E 18 1E	dd mm rr ff mm rr ff mm rr	6 7 8	—	—	—	—	—	—	—	—
BSET (opr) (msk)	Set Bit(s)	M + mm ⇒ M	DIR IND,X IND,Y	14 1C 18 1C	dd mm ff mm ff mm	6 7 8	—	—	—	—	Δ	Δ	0	—
BSR (rel)	Branch to Subroutine	See Figure 3–2	REL	8D	rr	6	—	—	—	—	—	—	—	—
BVC (rel)	Branch if Overflow Clear	? V = 0	REL	28	rr	3	—	—	—	—	—	—	—	—
BVS (rel)	Branch if Overflow Set	? V = 1	REL	29	rr	3	—	—	—	—	—	—	—	—
CBA	Compare A to B	A – B	INH	11	—	2	—	—	—	—	Δ	Δ	Δ	Δ
CLC	Clear Carry Bit	0 ⇒ C	INH	0C	—	2	—	—	—	—	—	—	—	0
CLI	Clear Interrupt Mask	0 ⇒ I	INH	0E	—	2	—	—	—	0	—	—	—	—
CLR (opr)	Clear Memory Byte	0 ⇒ M	EXT IND,X IND,Y	7F 6F 18 6F	hh ll ff ff	6 6 7	—	—	—	—	0	1	0	0
CLRA	Clear Accumulator A	0 ⇒ A	A INH	4F	—	2	—	—	—	—	0	1	0	0
CLRB	Clear Accumulator B	0 ⇒ B	B INH	5F	—	2	—	—	—	—	0	1	0	0
CLV	Clear Overflow Flag	0 ⇒ V	INH	0A	—	2	—	—	—	—	—	—	0	—
CMPA (opr)	Compare A to Memory	A – M	A IMM A DIR A EXT A IND,X A IND,Y	81 91 B1 A1 18 A1	ii dd hh ll ff ff	2 3 4 4 5	—	—	—	—	Δ	Δ	Δ	Δ
CMPB (opr)	Compare B to Memory	B – M	B IMM B DIR B EXT B IND,X B IND,Y	C1 D1 F1 E1 18 E1	ii dd hh ll ff ff	2 3 4 4 5	—	—	—	—	Δ	Δ	Δ	Δ

A normal mode is selected when MODB is logic one during reset. One of three reset vectors is fetched from address $FFFA–$FFFF, and program execution begins from the address indicated by this vector. If MODB is logic zero during reset, the special mode reset vector is fetched from addresses $BFFA–$BFFF and software has access to special test features. Refer to **SECTION 5 RESETS AND INTERRUPTS** for information regarding reset vectors.

4.3.1.1 HPRIO Register

Bits in the HPRIO register select the highest priority interrupt level, select whether bootstrap ROM is present, and control visibility of internal reads by the CPU. After reset, MDA and SMOD select the operating mode.

HPRIO — Highest Priority I-Bit Interrupt and Miscellaneous **$103C**

	Bit 7	6	5	4	3	2	1	Bit 0	
	RBOOT*	SMOD*	MDA*	IRV	PSEL3	PSEL2	PSEL1	PSEL0	
RESET:	0	0	0	0	0	1	1	0	Single Chip
	0	0	1	0	0	1	1	0	Expanded
	1	1	0	1	0	1	1	0	Bootstrap
	0	1	1	1	0	1	1	0	Special Test

*Reset states of RBOOT, SMOD, and MDA bits depend on hardware mode selection. Refer to **Table 4-3**.

RBOOT — Read Bootstrap ROM

Set to one out of reset in bootstrap mode. Valid while in special modes only. Can be read anytime. Can only be written in special modes.

0 = Bootloader ROM disabled and not in map
1 = Bootloader ROM enabled and in map at $BF00–$BFFF

SMOD and MDA — Special Mode Select and Mode Select A

The initial value of SMOD is the inverse of the logic level present on the MODB pin at the rising edge of reset. The initial value of MDA equals the logic level present on the MODA pin at the rising edge of reset. These two bits can be read at any time. They can be written at any time in special modes. Neither bit can be written is normal modes. SMOD cannot be set once it has been cleared. Refer to **Table 4-3**.

IRV — Internal Read Visibility

IRV can be written at any time in special modes (SMOD = 1). In normal modes (SMOD = 0) IRV can be written only once. In expanded and test modes, IRV determines whether internal read visibility is on or off. In single-chip and bootstrap modes, IRV has no meaning or effect.

0 = No internal read visibility on external bus
1 = Data from internal reads is driven out the external data bus.

PSEL[3:0] — Priority Select Bits [3:0]

Refer to **5.3.1 Highest Priority Interrupt and Miscellaneous Register**.

```
ROWE    LDAB    #$0E        ROW=1, ERASE=1, EELAT=1, EEPGM=0
        STAB    $103B       Set to ROW erase mode
        STAB    0,X         Store any data to any address in ROW
        LDAB    #$0F        ROW=1, ERASE=1, EELAT=1, EEPGM=1
        STAB    $103B       Turn on high voltage
        JSR     DLY10       Delay 10 ms
        CLR     $103B       Turn off high voltage and set to READ mode
```

4.4.1.4 EEPROM Byte Erase

The following is an example of how to erase a single byte of EEPROM and assumes that index register X contains the address of the byte to be erased.

```
BYTEE   LDAB    #$16        BYTE=1, ROW=0, ERASE=1, EELAT=1, EEPGM=0
        STAB    $103B       Set to BYTE erase mode
        STAB    0,X         Store any data to address to be erased
        LDAB    #$17        BYTE=1, ROW=0, ERASE=1, EELAT=1, EEPGM=1
        STAB    $103B       Turn on high voltage
        JSR     DLY10       Delay 10 ms
        CLR     $103B       Turn off high voltage and set to READ mode
```

4.4.2 PPROG EEPROM Programming Control Register

Bits in PPROG register control parameters associated with EEPROM programming.

PPROG — EEPROM Programming Control **$103B**

	Bit 7	6	5	4	3	2	1	Bit 0
	ODD	EVEN	—	BYTE	ROW	ERASE	EELAT	EEPGM
RESET:	0	0	0	0	0	0	0	0

ODD — Program Odd Rows in Half of EEPROM (TEST)

EVEN — Program Even Rows in Half of EEPROM (TEST)

Bit 5 — Not implemented
Always reads zero

BYTE — Byte/Other EEPROM Erase Mode
0 = Row or bulk erase mode used
1 = Erase only one byte of EEPROM

ROW — Row/All EEPROM Erase Mode (only valid when BYTE = 0)
0 = All 512 bytes of EEPROM erased
1 = Erase only one 16-byte row of EEPROM

For a description of the bits contained in the CONFIG register refer to **4.3.2.1 CONFIG Register**.

4.5 Chip Selects

The function of the chip selects is to minimize the amount of external glue logic needed to interface the MCU to external devices. The MC68HC11F1 has four software configured chip selects that can be enabled in expanded modes. The chip selects for I/O (CSIO1 and CSIO2) are used for I/O expansion. The program chip select ($\overline{\text{CSPROG}}$) is used with an external memory that contains the program code and reset vectors. The general-purpose chip select (CSGEN) is the most flexible and is used to enable external devices.

Such factors as polarity, block size, base address and clock stretching can be controlled using the four chip-select control registers. When a port G pin is not used for chip select functions it can be used for general-purpose I/O.

When enabled, a chip select signal is asserted whenever the CPU makes an access to a designated range of addresses. Bus control signals and chip select signals are synchronous with the external E clock signal. For more information refer to Table A–7. Expansion Bus Timing in **APPENDIX A ELECTRICAL CHARACTERISTICS**. The length of the external E clock cycle to which the external device is synchronized can be stretched to accommodate devices that are slower than the MCU.

4.5.1 Program Chip Select

The program chip select ($\overline{\text{CSPROG}}$) is active in the range of memory where the main program exists. Refer to **Figure 4-3**.

When enabled, the $\overline{\text{CSPROG}}$ is active during address valid time and is an active-low signal. Although the general-purpose chip select has priority over the program chip select, $\overline{\text{CSPROG}}$ can be raised to a higher priority level by setting the GCSPR bit in CSCTL register. Bits in CSCTL enable the program chip select and determine its address range and priority level. Bits in CSSTRH select from zero to three clock cycles of delay.

4.5.2 I/O Chip Selects

The I/O chip selects (CSIO1 and CSIO2) are fixed in size and fill the remainder of the 4-Kbyte block occupied by the register block. CSIO1 is mapped at $x060–$x7FF and CSIO2 is mapped at $x800–$xFFF, where “x” corresponds to the high-order nibble of the register block base address, represented by the value contained in REG[3:0] in the INIT register.

Bits in the CSCTL register determine the polarity of the active state and enable both I/O chip selects. Bits in CSGSIZ select whether each chip select is active for address-valid or E-valid time. Bits in CSSTRH select from zero to three clock cycles of delay. Refer to **Figure 4-3**.

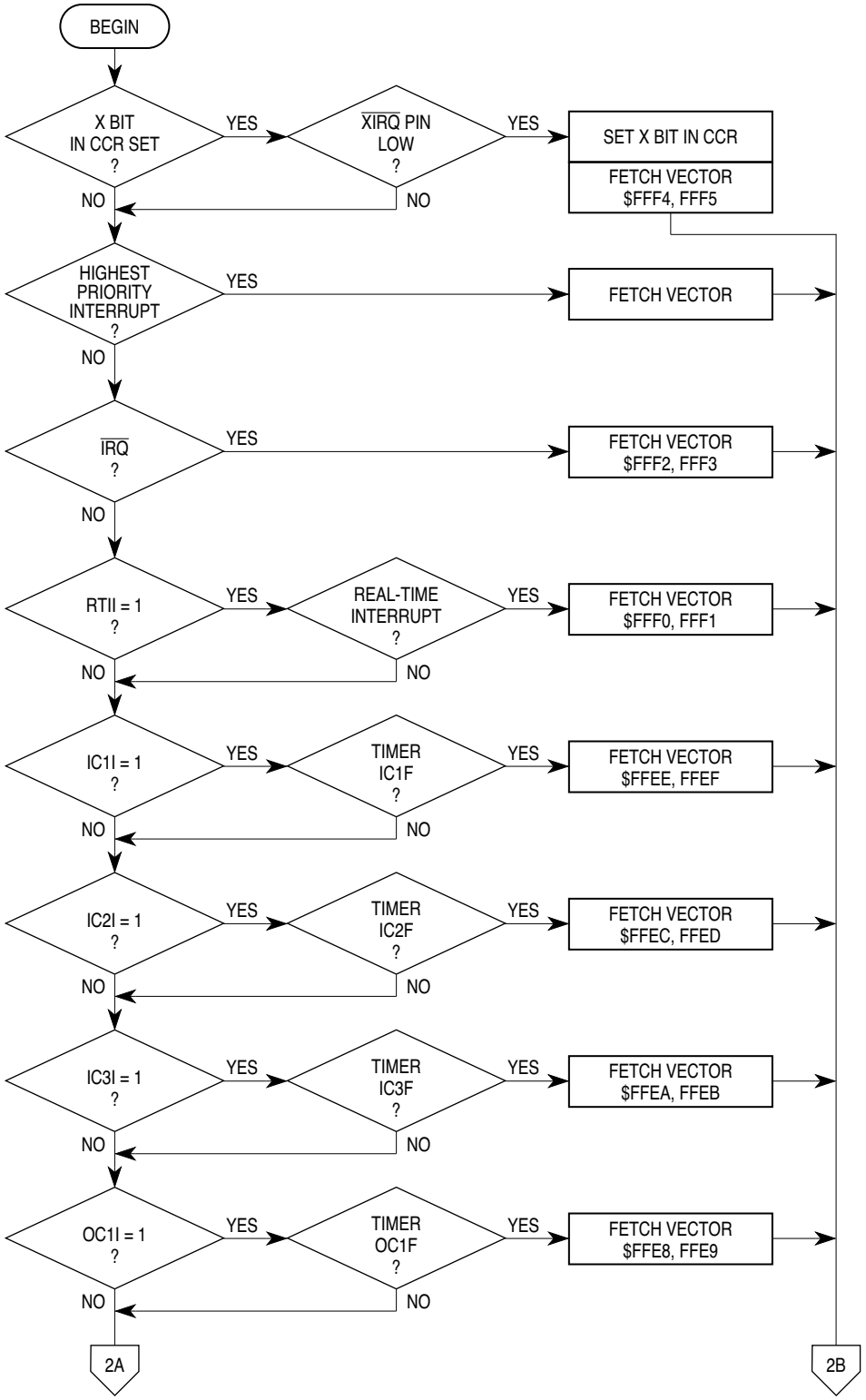

Figure 5-3 Interrupt Priority Resolution (1 of 2)

Because the oscillator is stopped in STOP mode, a restart delay may be imposed to allow oscillator stabilization upon leaving STOP. If the internal oscillator is being used, this delay is required; however, if a stable external oscillator is being used, the DLY control bit can be used to bypass this start-up delay. The DLY control bit is set by reset and can be optionally cleared during initialization. If the DLY equal to zero option is used to avoid start-up delay on recovery from STOP, then reset should not be used as the means of recovering from STOP, as this causes DLY to be set again by reset, imposing the restart delay. This same delay also applies to power-on reset, regardless of the state of the DLY control bit, but does not apply to a reset while the clocks are running.

DDRA — Data Direction Register for Port A **$1001**

	Bit 7	6	5	4	3	2	1	Bit 0
	DDA7	DDA6	DDA5	DDA4	DDA3	DDA2	DDA1	DDA0
RESET:	0	0	0	0	0	0	0	0

DDA[7:0] — Data Direction for Port A
0 = Input
1 = Output

NOTE

To enable PA3 as fourth input capture, set the I4/O5 bit in the PACTL register. Otherwise, PA3 is configured as a fifth output compare out of reset, with bit I4/O5 being cleared. If the DDA3 bit is set (configuring PA3 as an output), and IC4 is enabled, writes to PA3 cause edges on the pin to result in input captures. Writing to TI4/O5 has no effect when the TI4/O5 register is acting as IC4. PA7 drives the pulse accumulator input but also can be configured for general-purpose I/O, or output compare. Note that even when PA7 is configured as an output, the pin still drives the pulse accumulator input.

6.2 Port B

Reset state is mode dependent. In single-chip or bootstrap modes, port B pins are general-purpose outputs. In expanded and test modes, port B pins are high-order address outputs and PORTB is not in the memory map.

PORTB — Port B Data **$1004**

	Bit 7	6	5	4	3	2	1	Bit 0
	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
S. Chip or Boot:	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
RESET:	0	0	0	0	0	0	0	0
Expan. or Test:	ADDR15	ADDR14	ADDR13	ADDR12	ADDR11	ADDR10	ADDR9	ADDR8

6.3 Port C

Reset state is mode dependent. In single-chip and bootstrap modes, port C pins are high-impedance inputs. It is customary to have an external pull-up resistor on lines that are driven by open-drain devices. In expanded or test modes, port C pins are data bus inputs/outputs and PORTC is not in the memory map. The R/$\overline{W}$ signal is used to control the direction of data transfers.

The CWOM control bit in the OPT2 register disables port C's P-channel output drivers. Because the N-channel driver is not affected by CWOM, setting CWOM causes port C to become an open-drain-type output port suitable for wired-OR operation. In wired-OR mode, (PORTC bits are at logic level zero), pins are actively driven low by the N-channel driver. When a port C bit is at logic level one, the associated pin is in a high-

7.5 SCI Error Detection

Three error conditions, SCDR overrun, received bit noise, and framing can occur during generation of SCI system interrupts. Three bits (OR, NF, and FE) in the serial communications status register (SCSR) indicate if one of these error conditions exists.

The overrun error (OR) bit is set when the next byte is ready to be transferred from the receive shift register to the SCDR and the SCDR is already full (RDRF bit is set). When an overrun error occurs, the data that caused the overrun is lost and the data that was already in SCDR is not disturbed. The OR is cleared when the SCSR is read (with OR set), followed by a read of the SCDR.

The noise flag (NF) bit is set if there is noise on any of the received bits, including the start and stop bits. The NF bit is not set until the RDRF flag is set. The NF bit is cleared when the SCSR is read (with FE equal to one) followed by a read of the SCDR.

When no stop bit is detected in the received data character, the framing error (FE) bit is set. FE is set at the same time as the RDRF. If the byte received causes both framing and overrun errors, the processor only recognizes the overrun error. The framing error flag inhibits further transfer of data into the SCDR until it is cleared. The FE bit is cleared when the SCSR is read (with FE equal to one) followed by a read of the SCDR.

7.6 SCI Registers

There are five addressable registers associated with the SCI. SCCR1, SCCR2, and BAUD are control registers. SCDR is the SCI data register and SCSR is the SCI status register. Refer to the BAUD register description as well as the block diagram for the baud rate generator.

7.6.1 Serial Communications Data Register

SCDR is a parallel register that performs two functions. It is the receive data register when it is read, and the transmit data register when it is written. Reads access the receive data buffer and writes access the transmit data buffer. Receive and transmit are double buffered.

SCDR — SCI Data Register **$102F**

	Bit 7	6	5	4	3	2	1	Bit 0
	R7/T7	R6/T6	R5/T5	R4/T4	R3/T3	R2/T2	R1/T1	R0/T0
RESET:	I	I	I	I	I	I	I	I

7.6.2 Serial Communications Control Register 1

The SCCR1 register provides the control bits that determine word length and select the method used for the wakeup feature.

SCCR1 — SCI Control Register 1 **$102C**

	Bit 7	6	5	4	3	2	1	Bit 0
	R8	T8	—	M	WAKE	—	—	—
RESET:	I	I	0	0	0	0	0	0

RWU — Receiver Wakeup Control

0 = Normal SCI receiver
1 = Wakeup enabled and receiver interrupts inhibited

SBK — Send Break

At least one character time of break is queued and sent each time SBK is written to one. As long as the SBK bit is set, break characters are queued and sent. More than one break may be sent if the transmitter is idle at the time the SBK bit is toggled on and off, as the baud rate clock edge could occur between writing the one and writing the zero to SBK.

0 = Break generator off
1 = Break codes generated

7.6.4 Serial Communication Status Register

The SCSR provides inputs to the interrupt logic circuits for generation of the SCI system interrupt.

SCSR — SCI Status Register **$102E**

	Bit 7	6	5	4	3	2	1	Bit 0
	TDRE	TC	RDRF	IDLE	OR	NF	FE	—
RESET:	1	1	0	0	0	0	0	0

TDRE — Transmit Data Register Empty Flag

This flag is set when SCDR is empty. Clear the TDRE flag by reading SCSR and then writing to SCDR.

0 = SCDR busy
1 = SCDR empty

TC — Transmit Complete Flag

This flag is set when the transmitter is idle (no data, preamble, or break transmission in progress). Clear the TC flag by reading SCSR and then writing to SCDR.

0 = Transmitter busy
1 = Transmitter idle

RDRF — Receive Data Register Full Flag

This flag is set if a received character is ready to be read from SCDR. Clear the RDRF flag by reading SCSR and then reading SCDR.

0 = SCDR empty
1 = SCDR full

IDLE — Idle Line Detected Flag

This flag is set if the RxD line is idle. Once cleared, IDLE is not set again until the RxD line has been active and becomes idle again. The IDLE flag is inhibited when RWU = 1. Clear IDLE by reading SCSR and then reading SCDR.

0 = RxD line is active
1 = RxD line is idle

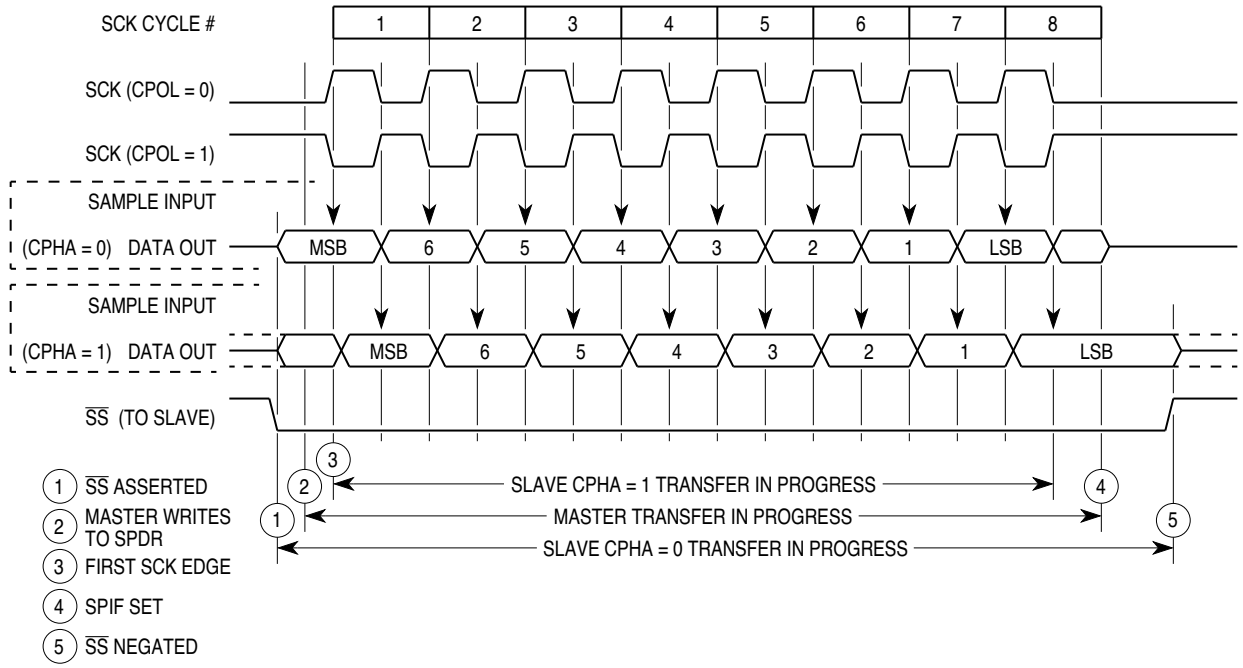

Figure 8-2 SPI Transfer Format

8.2.1 Clock Phase and Polarity Controls

Software can select one of four combinations of serial clock phase and polarity using two bits in the SPI control register (SPCR). The clock polarity is specified by the CPOL control bit, which selects an active high or active low clock, and has no significant effect on the transfer format. The clock phase (CPHA) control bit selects one of two different transfer formats. The clock phase and polarity should be identical for the master SPI device and the communicating slave device. In some cases, the phase and polarity are changed between transfers to allow a master device to communicate with peripheral slaves having different requirements.

When CPHA equals zero, the $\overline{SS}$ line must be negated and reasserted between each successive serial byte. Also, if the slave writes data to the SPI data register (SPDR) while $\overline{SS}$ is low, a write collision error results.

When CPHA equals one, the $\overline{SS}$ line can remain low between successive transfers.

8.3 SPI Signals

The following paragraphs contain descriptions of the four SPI signals: master in slave out (MISO), master out slave in (MOSI), serial clock (SCK), and slave select ($\overline{SS}$).

Any SPI output line must have its corresponding data direction bit in DDRD register set. If the DDR bit is clear, that line is disconnected from the SPI logic and becomes a general-purpose input. All SPI input lines are forced to act as inputs regardless of the state of the corresponding DDR bits in DDRD register.

OC1M — Output Compare 1 Mask **$100C**

	Bit 7	6	5	4	3	2	1	Bit 0
	OC1M7	OC1M6	OC1M5	OC1M4	OC1M3	—	—	—
RESET:	0	0	0	0	0	0	0	0

OC1M[7:3] — Output Compare Masks
0 = OC1 is disabled.
1 = OC1 is enabled to control the corresponding pin of port A

Bits [2:0] — Not implemented
Always read zero

9.3.4 Output Compare Data Register

Use this register with OC1 to specify the data that is to be stored on the affected pin of port A after a successful OC1 compare. When a successful OC1 compare occurs, a data bit in OC1D is stored in the corresponding bit of port A for each bit that is set in OC1M.

OC1D — Output Compare 1 Data **$100D**

	Bit 7	6	5	4	3	2	1	Bit 0
	OC1D7	OC1D6	OC1D5	OC1D4	OC1D3	—	—	—
RESET:	0	0	0	0	0	0	0	0

If OC1Mx is set, data in OC1Dx is output to port A bit x on successful OC1 compares.

Bits [2:0] — Not implemented
Always read zero

9.3.5 Timer Counter Register

The 16-bit read-only TCNT register contains the prescaled value of the 16-bit timer. A full counter read addresses the most significant byte (MSB) first. A read of this address causes the least significant byte (LSB) to be latched into a buffer for the next CPU cycle so that a double-byte read returns the full 16-bit state of the counter at the time of the MSB read cycle.

TCNT — Timer Counter **$100E, $100F**

$100E	Bit 15	14	13	12	11	10	9	Bit 8	TCNT (High)
$100F	Bit 7	6	5	4	3	2	1	Bit 0	TCNT (Low)

TCNT resets to $0000. In normal modes, TCNT is a read-only register.

9.3.6 Timer Control Register 1

The bits of this register specify the action taken as a result of a successful OCx compare.

Table 9-3 Timer Prescaler Selection

PR[1:0]	Prescaler
0 0	1
0 1	4
1 0	8
1 1	16

NOTE

Bits in TMSK2 correspond bit for bit with flag bits in TFLG2. Ones in TMSK2 enable the corresponding interrupt sources.

9.3.10 Timer Interrupt Flag Register 2

Bits in this register indicate when certain timer system events have occurred. Coupled with the four high-order bits of TMSK2, the bits of TFLG2 allow the timer subsystem to operate in either a polled or interrupt driven system. Each bit of TFLG2 corresponds to a bit in TMSK2 in the same position.

TFLG2 — Timer Interrupt Flag 2 **$1025**

	Bit 7	6	5	4	3	2	1	Bit 0
	TOF	RTIF	PAOVF	PAIF	—	—	—	—
RESET:	0	0	0	0	0	0	0	0

Clear flags by writing a one to the corresponding bit position(s).

TOF — Timer Overflow Interrupt Flag
Set when TCNT changes from $FFFF to $0000

RTIF — Real-Time (Periodic) Interrupt Flag
Refer to **9.4 Real-Time Interrupt**.

PAOVF — Pulse Accumulator Overflow Interrupt Flag
Refer to **9.6 Pulse Accumulator**.

PAIF — Pulse Accumulator Input Edge Interrupt Flag
Refer to **9.6 Pulse Accumulator**.

Bits [3:0] — Not implemented
Always read zero

9.4 Real-Time Interrupt

The real-time interrupt (RTI) feature, used to generate hardware interrupts at a fixed periodic rate, is controlled and configured by two bits (RTR1 and RTR0) in the pulse accumulator control (PACTL) register. The RTII bit in the TMSK2 register enables the interrupt capability. The four different rates available are a product of the MCU oscillator frequency and the value of bits RTR[1:0]. Refer to **Table 9-4**, which shows the periodic real-time interrupt rates.

Table 9-4 RTI Rate Selection

RTR[1:0]	E = 1 MHz	E = 2 MHz	E = 3 MHz	E = 4 MHz	E = X MHz
0 0	8.192 ms	4.096 ms	2.731 ms	2.048 ms	$(2^{13}/E)$
0 1	16.384 ms	8.192 ms	5.461 ms	4.096 ms	$(2^{14}/E)$
1 0	32.768 ms	16.384 ms	10.923 ms	8.192 ms	$(2^{15}/E)$
1 1	65.536 ms	32.768 ms	21.845 ms	16.384 ms	$(2^{16}/E)$

The clock source for the RTI function is a free-running clock that cannot be stopped or interrupted except by reset. This clock causes the time between successive RTI time-outs to be a constant that is independent of the software latencies associated with flag clearing and service. For this reason, an RTI period starts from the previous time-out, not from when RTIF is cleared.

Every time-out causes the RTIF bit in TFLG2 to be set, and if RTII is set, an interrupt request is generated. After reset, one entire RTI period elapses before the RTIF flag is set for the first time. Refer to the TMSK2, TFLG2, and PACTL registers.

9.4.1 Timer Interrupt Mask Register 2

This register contains the real-time interrupt enable bits.

TMSK2 — Timer Interrupt Mask Register 2 **$1024**

	Bit 7	6	5	4	3	2	1	Bit 0
	TOI	RTII	PAOVI	PAII	—	—	PR1	PR0
RESET:	0	0	0	0	0	0	0	0

TOI — Timer Overflow Interrupt Enable
0 = TOF interrupts disabled
1 = Interrupt requested when TOF is set to one

RTII — Real-Time Interrupt Enable
0 = RTIF interrupts disabled
1 = Interrupt requested when RTIF set to one

PAOVI — Pulse Accumulator Overflow Interrupt Enable
Refer to **9.6 Pulse Accumulator**.

PAII — Pulse Accumulator Input Edge
Refer to **9.6 Pulse Accumulator**.

PR[1:0] — Timer Prescaler Select
Refer to **Table 9-4**.

NOTE

Bits in TMSK2 correspond bit for bit with flag bits in TFLG2. Ones in TMSK2 enable the corresponding interrupt sources.

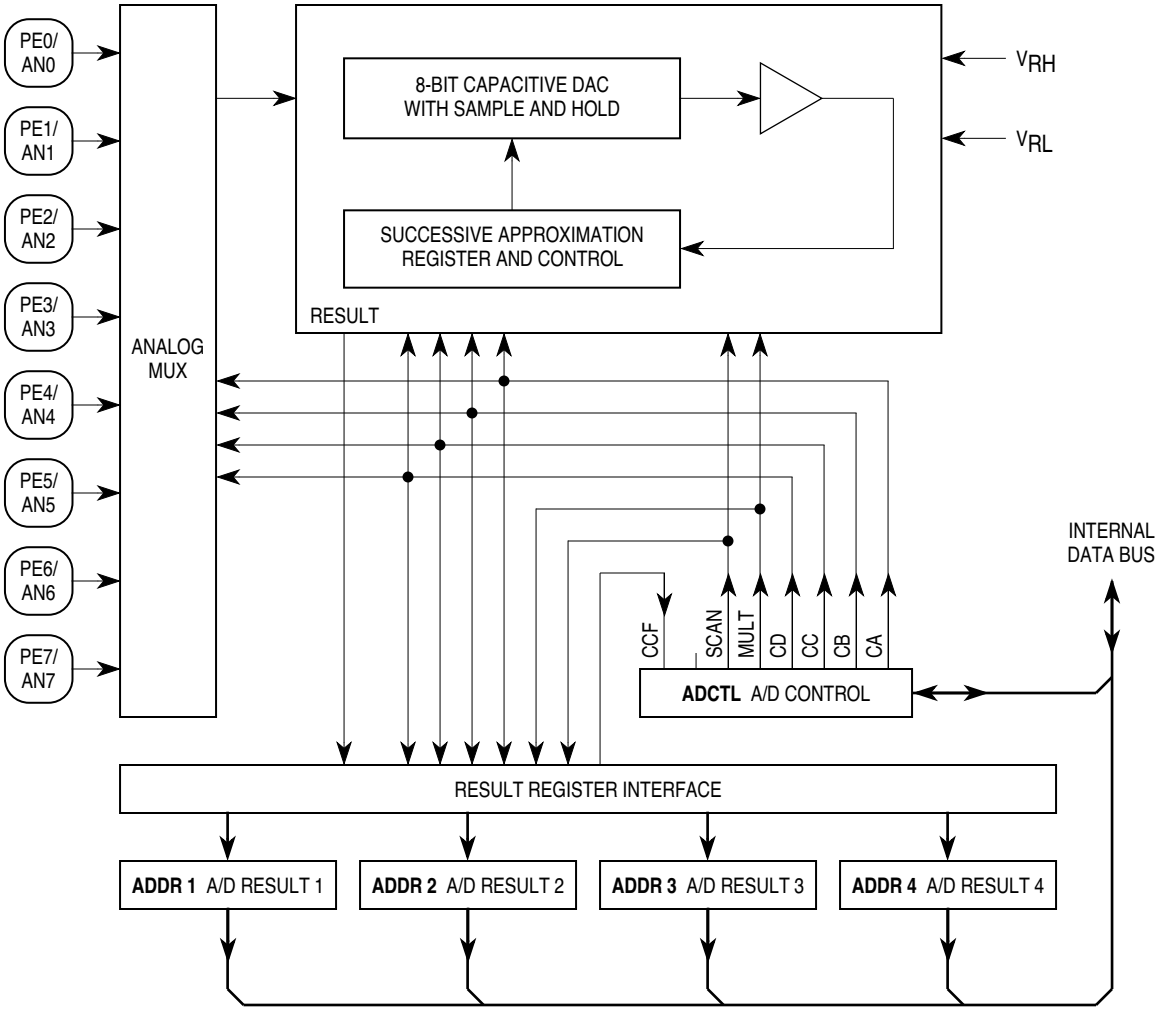

Figure 10-1 A/D Converter Block Diagram

Port E pins can also be used as digital inputs. Reads of port E pins are not recommended during the sample portion of an A/D conversion cycle, when the gate signal to the N-channel input gate is on. Because no P-channel devices are directly connected to either input pins or reference voltage pins, voltages above V_{DD} do not cause a latchup problem, although current should be limited according to maximum ratings. Refer to **Figure 10-2**, which is a functional diagram of an input pin.

10.4 Channel Assignments

The multiplexer allows the A/D converter to select one of sixteen analog signals. Eight of these channels correspond to port E input lines, four of the channels are internal reference points or test functions, and four channels are reserved. Refer to **Table 10-1**.

Table 10-1 A/D Converter Channel Assignments

Channel Number	Channel Signal	Result in ADRx if MULT = 1
1	AN0	ADR1
2	AN1	ADR2
3	AN2	ADR3
4	AN3	ADR4
5	AN4	ADR1
6	AN5	ADR2
7	AN6	ADR3
8	AN7	ADR4
9	Reserved	—
10	Reserved	—
11	Reserved	—
12	Reserved	—
13	V_{RH}*	ADR1
14	V_{RL}*	ADR2
15	$(V_{RH})/2$*	ADR3
16	Reserved*	ADR4

*Used for factory testing

10.5 Single-Channel Operation

There are two types of single-channel operation. When SCAN = 0, the first type, the single selected channel is converted four consecutive times. The first result is stored in A/D result register 1 (ADR1), and the fourth result is stored in ADR4. After the fourth conversion is complete, all conversion activity is halted until a new conversion command is written to the ADCTL register. In the second type of single-channel operation, SCAN = 1, conversions continue to be performed on the selected channel with the fifth conversion being stored in register ADR1 (overwriting the first conversion result), the sixth conversion overwriting ADR2, and so on.

10.6 Multiple-Channel Operation

There are two types of multiple-channel operation. When SCAN = 0, the first type, a selected group of four channels is converted one time each. The first result is stored in A/D result register 1 (ADR1), and the fourth result is stored in ADR4. After the fourth conversion is complete, all conversion activity is halted until a new conversion command is written to the ADCTL register. In the second type of multiple-channel operation, SCAN = 1, conversions continue to be performed on the selected group of channels with the fifth conversion being stored in register ADR1 (replacing the earlier conversion result for the first channel in the group), the sixth conversion overwriting ADR2, and so on.

Table A-3 DC Electrical Characteristics

V_{DD} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, unless otherwise noted

Characteristic	Symbol	Min	Max	Unit
Output Voltage (Note 1) All Outputs except XTAL All Outputs Except XTAL, $\overline{\text{RESET}}$, and MODA I_{Load} = ± 10.0 µA	V_{OL} V_{OH}	— V_{DD} – 0.1	0.1 —	V V
Output High Voltage (Note 1) All Outputs Except XTAL, $\overline{\text{RESET}}$, and MODA I_{Load} = – 0.8 mA, V_{DD} = 4.5 V	V_{OH}	V_{DD} – 0.8	—	V
Output Low Voltage All Outputs Except XTAL I_{Load} = 1.6 mA	V_{OL}	—	0.4	V
Input High Voltage All Inputs Except $\overline{\text{RESET}}$ $\overline{\text{RESET}}$	V_{IH}	0.7 x V_{DD} 0.8 x V_{DD}	V_{DD} + 0.3 V_{DD} + 0.3	V V
Input Low Voltage All Inputs	V_{IL}	V_{SS} – 0.3	0.2 x V_{DD}	V
I/O Ports, Three-State Leakage Ports A, B, C, D, F, G $V_{in} = V_{IH}$ or V_{IL} MODA/$\overline{\text{LIR}}$, $\overline{\text{RESET}}$	I_{OZ}	—	±10	µA
Input Leakage Current (Note 2) $V_{in} = V_{DD}$ or V_{SS} $\overline{\text{IRQ}}$, $\overline{\text{XIRQ}}$ on standard devices $V_{in} = V_{DD}$ or V_{SS} MODB/V_{STBY}, $\overline{\text{XIRQ}}$ on EPROM devices	I_{in}	— —	±1 ±10	µA µA
Input Current with Pull-Up Resistors $V_{in} = V_{IL}$ Ports B, F, and G	I_{ipr}	100	500	µA
RAM Standby Voltage Power down	V_{SB}	4.0	V_{DD}	V
RAM Standby Current Power down	I_{SB}	—	20	µA
Input Capacitance PE[7:0], $\overline{\text{IRQ}}$, $\overline{\text{XIRQ}}$, EXTAL Ports A, B, C, D, F, G, MODA/$\overline{\text{LIR}}$, $\overline{\text{RESET}}$	C_{in}	— —	8 12	pF pF
Output Load Capacitance All Outputs Except PD[4:1], 4XOUT, XTAL, MODA/$\overline{\text{LIR}}$ PD[4:1] 4XOUT	C_L	— — —	90 200 30	pF pF pF

Characteristic	Symbol	2 MHz	3 MHz	4 MHz	Unit
Maximum Total Supply Current (Note 3) **RUN:** Expanded Mode	I_{DD} 27	 38	 50	 mA
WAIT: (All Peripheral Functions Shut Down) Expanded Mode	W_{IDD} 15	 20	 25	 mA
STOP: No Clocks, Expanded Mode	S_{IDD} 50	 50	 50	 µA
Maximum Power Dissipation Expanded Mode	P_D 149	 209	 275	 mW

NOTES:

1. V_{OH} specification for $\overline{\text{RESET}}$ and MODA is not applicable because they are open-drain pins. V_{OH} specification not applicable to ports C and D in wired-OR mode.
2. Refer to A/D specification for leakage current for port E.
3. EXTAL is driven with a square wave, and
   t_{cyc} = 500 ns for 2 MHz rating;
   t_{cyc} = 333 ns for 3 MHz rating;
   t_{cyc} = 250 ns for 4 MHz rating;
   $V_{IL} \le 0.2$ V; $V_{IH} \ge V_{DD} – 0.2$ V; No dc loads.

Table A-6 Analog-To-Digital Converter Characteristics

V_{DD} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, 750 kHz ≤ E ≤ 3.0 MHz, unless otherwise noted

Characteristic	Parameter	Min	Absolute	2.0 MHz	3.0 MHz	4.0 MHz	Unit
				Max	Max	Max	
Resolution	Number of Bits Resolved by A/D Converter	—	8	—	—	—	Bits
Non-Linearity	Maximum Deviation from the Ideal A/D Transfer Characteristics	—	—	± 1	± 1	± 1	LSB
Zero Error	Difference Between the Output of an Ideal and an Actual for Zero Input Voltage	—	—	± 1	± 1	± 1	LSB
Full Scale Error	Difference Between the Output of an Ideal and an Actual A/D for Full-Scale Input Voltage	—	—	± 1	± 1	± 1	LSB
Total Unadjusted Error	Maximum Sum of Non-Linearity, Zero Error, and Full-Scale Error	—	—	± 1/2	± 1 1/2	± 1 1/2	LSB
Quantization Error	Uncertainty Because of Converter Resolution	—	—	± 1/2	± 1/2	± 1/2	LSB
Absolute Accuracy	Difference Between the Actual Input Voltage and the Full-Scale Weighted Equivalent of the Binary Output Code, All Error Sources Included	—	—	± 1	± 2	± 2	LSB
Conversion Range	Analog Input Voltage Range	V_{RL}	—	V_{RH}	V_{RH}	V_{RH}	V
V_{RH}	Maximum Analog Reference Voltage (Note 2)	V_{RL}	—	V_{DD} + 0.1	V_{DD} + 0.1	V_{DD} + 0.1	V
V_{RL}	Minimum Analog Reference Voltage (Note 2)	V_{SS} –0.1	—	V_{RH}	V_{RH}	V_{RH}	V
ΔV_R	Minimum Difference between V_{RH} and V_{RL} (Note 2)	3	—	—	—	—	V
Conversion Time	Total Time to Perform a Single Analog-to-Digital Conversion: E Clock Internal RC Oscillator	 — —	 32 —	 — t_{cyc} + 32	 — t_{cyc} + 32	 — t_{cyc} + 32	 t_{cyc} µs
Monotonicity	Conversion Result Never Decreases with an Increase in Input Voltage and has no Missing Codes		Guaranteed				
Zero Input Reading	Conversion Result when $V_{in} = V_{RL}$	00	—	—	—	—	Hex
Full Scale Reading	Conversion Result when $V_{in} = V_{RH}$	—	—	FF	FF	FF	Hex
Sample Acquisition Time	Analog Input Acquisition Sampling Time: E Clock Internal RC Oscillator	 — —	 12 —	 — 12	 — 12	 — 12	 t_{cyc} µs
Sample/Hold Capacitance	Input Capacitance during Sample PE[7:0]	—	20 (Typ)	—	—	—	pF
Input Leakage	Input Leakage on A/D Pins PE[7:0] V_{RL}, V_{RH}	— —	— —	400 1.0	400 1.0	400 1.0	nA µA

NOTES:

1. For f_{op} < 2 MHz, source impedances should equal approximately 10 kΩ. For f_{op} ≥ 2 MHz, source impedances should equal approximately 5 kΩ – 10 kΩ. Source impedances greater than 10 kΩ affect accuracy adversely because of input leakage.
2. Performance verified down to 2.5 V ΔV_R, but accuracy is tested and guaranteed at ΔV_R = 5 V ± 10%